

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Blackshear et al.

Serial No.: 10/056,256

Group Art Unit: 2811

Filed: January 24, 2002

Examiner: Unknown

For: VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES

Assistant Commissioner of Patents  
Washington, D.C. 20231

**SUBMISSION OF FORMAL DRAWINGS**

Sir:

Submitted herewith is one (1) sheet of formal drawings comprising Figs. 1-3 for the above-referenced patent application. Acknowledgment of receipt is respectfully requested. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully Submitted,



Frederick W. Gibb, III  
Reg. No. 37,629

Date: 3/27/02  
McGinn & Gibb, PLLC  
2568-A Riva Road, Suite 304  
Annapolis, Maryland 21401  
(410) 573-1545  
Customer No. 29154

RECEIVED  
APR 12 2002  
TECHNOLOGY CENTER 2800



2811  
13  
5-28-02

## CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)

Applicant(s): Blackshear et al.

Docket No.

FIS9-2000-0273-US1

Serial No.  
10/056,256Filing Date  
January 24, 2002Examiner  
UnknownGroup Art Unit  
2811

Invention: VERTICALLY STACKED MEMORY CHIPS IN FBGA PACKAGES

I hereby certify that this Submission of Formal Drawings

(Identify type of correspondence)

is being deposited with the United States Postal Service as first class mail in an envelope addressed to: The

Assistant Commissioner for Patents, Washington, D.C. 20231 on

March 27, 2002

(Date)

Frederick W. Gibb, III

(Typed or Printed Name of Person Mailing Correspondence)

(Signature of Person Mailing Correspondence)

Note: Each paper must have its own certificate of mailing.

RECEIVED

APR 12 2002

TECHNOLOGY CENTER 2800